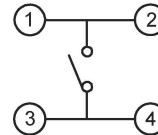
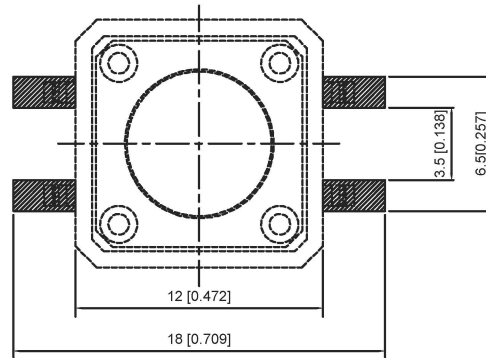
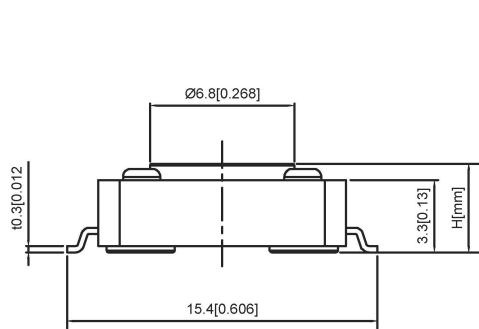


CIRCUIT DIAGRAM



Code-x	H	Code-x	H
A	4.3	O	11.0
B	4.5	P	11.5
C	5.0	Q	12
D	5.5	R	12.5
E	6.0	S	13.0
F	6.5	T	13.5
G	7.0	U	14.0
H	7.5	V	15.0
I	8.0	W	15.5
J	8.5	X	16
K	9.0	Y	17
L	9.5	Z	18
M	10.0	19	19
N	10.5		

P.C.B MOUNTING PATTERN DIMENSION  
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating: 50mA, 12V DC  
Contact Resistance: 100mΩ max  
Insulation Resistance: 100mΩ min. 500V DC  
Dielectric Strength: 250V AC/1minute  
Travel: 0.25mm  
Operating Temp: -30°C~+85°C  
Storage Temp: -30°C~+80°C

PAPT NO	TS-1103S-X-X
Operating Force	B:160gf C:260gf
Height	Code-x

④	Terminal	4	Brass (0.30t)	Plating silvering		
④	Contact	1	F.ag/Sus	Natural		
③	Base	1	Pa46			
②	Cover	1	Spcc	Plating Nickel		
①	Keystake	1	Pa46			
ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK

广东星坤科技股份有限公司

生效日期

文件工程章

REVISIONS	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES

DSND		DATE		SCALE: N/A	MODEL TYPE: TACT SWITCH
DWN		DATE		VIEW:	PART NO.:
CHKD		DATE		UNIT: mm/in	DWG NO.: TS-1103S-X-X
APPD		DATE		SIZE: A4	WEIGHT 1.0g SHEET 1/1 REVISION A0
XKB INDUSTRIAL PRECISION CO., LIMITED					

单击下面可查看定价，库存，交付和生命周期等信息

[>>XKB Connectivity\(中国星坤\)](#)